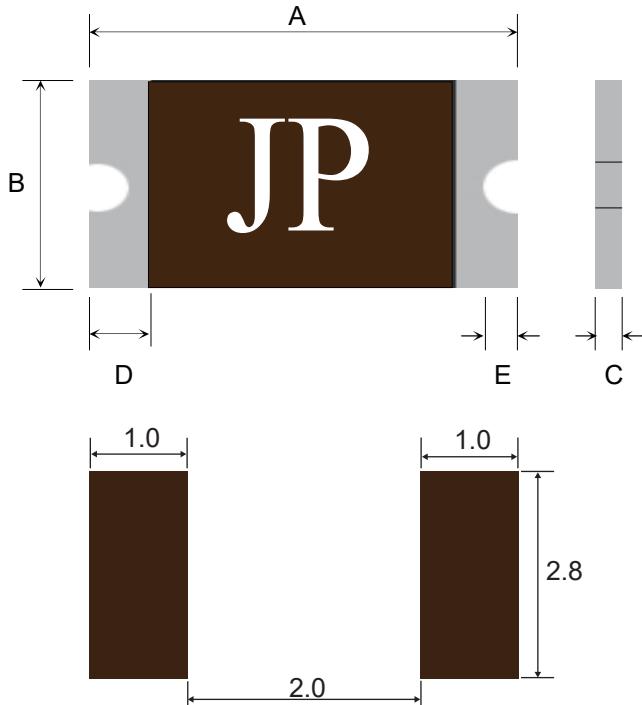


Specification Sheet

Terminal Pad Solderability

Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.

Terminal Pad Materials

Tin-Plated Nickel-Copper
Solder Material: Matte Tin (Sn)
Lead-Free, RoHS Compliant

Marking

Part Identification
ASMD1210SL500-21V = JP

Recommended Pad layout(mm)

Physical Dimensions(mm.)

Model	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.
ASMD1210SL500-21V	3.00	3.43	2.35	2.80	0.60	1.20	0.25	0.75	0.10

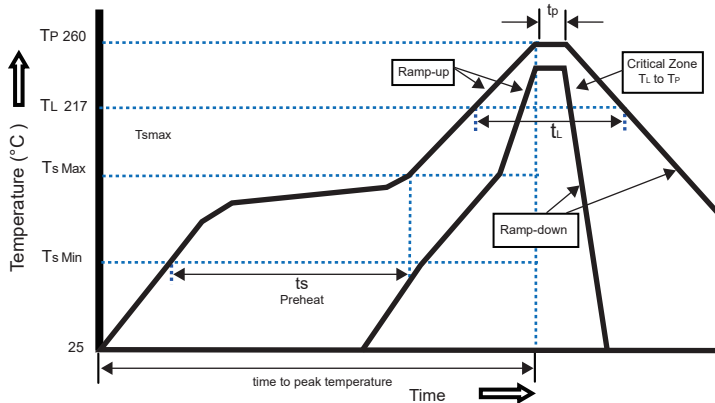
Electrical Characteristics

Model	I_{hold} @25°C (A)	I_{hold} @70°C (A)	V_{max} (V)	I_{max} (A)	P_d Typ. (W)	Thermal Cut Off (°C)		Resistance	
						3A		$R_{i min}$ (Ω)	R_{1max} (Ω)
						Min.	Max.		
ASMD1210SL500-21V	5.00	3.10	21.0	15.0	1.5	70	100	0.002	0.010

Thermal Derating Chart

Model	Maximum ambient operating temperature (T_{mao}) vs. hold current (I_{hold})				
	- 20°C	0°C	25°C	70°C	85°C
ASMD1210SL500-21V	6.00	5.70	5.00	3.10	1.70

Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate($T_{S_{Max}}$ to T_p)	3°C/s Max.
-Temperature Min($T_{S_{Min}}$)	150°C
Preheat -Temperature Max($T_{S_{Max}}$)	200°C
-Time($t_{S_{Min}}$ to $t_{S_{Max}}$)	60~180 s
Time maintained -Temperature(T_L)	217°C
above: -Time(t_L)	60~150 s
Peak/Classification Temperature(T_p)	260 $\pm$ 0/-5°C
Time within 5°C of actual peak temperature(t_p)	20~40 s
Ramp down rate	6°C/s Max.
Time 25°C to peak temperature	8 min. Max.

- ◆ All temperature refer to topside of the package, measured on the package body surface
- ◆ If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- ◆ Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead
- ◆ Recommended maximum paste thickness is 0.25mm (0.010inch)
- ◆ Devices can be cleaned using standard industry methods and solvents

Packaging Quantity

Model	Quantity
ASMD1210SL500-21V	3,500 pcs/reel